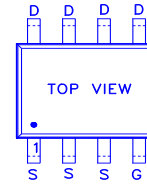
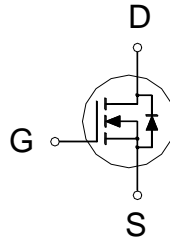


**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
60V	12.5mΩ	12A



G: GATE  
D: DRAIN  
S: SOURCE



**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	60	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	$I_D$	12	A
	$T_A = 70^\circ\text{C}$		10	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	40	
Avalanche Current		$I_{AS}$	39	
Avalanche Energy	L = 0.1mH	$E_{AS}$	76	mJ
Power Dissipation <sup>3</sup>	$T_A = 25^\circ\text{C}$	$P_D$	4	W
	$T_A = 70^\circ\text{C}$		2.6	
Junction & Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$t \leq 10\text{s}$	$R_{\theta JA}$		30	°C / W
Junction-to-Ambient	Steady-State	$R_{\theta JA}$		56	
Junction-to-Case	Steady-State	$R_{\theta JC}$		25	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

<sup>3</sup>The Power dissipation is based on  $R_{\theta JA} t \leq 10\text{s}$  value.

**ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)**

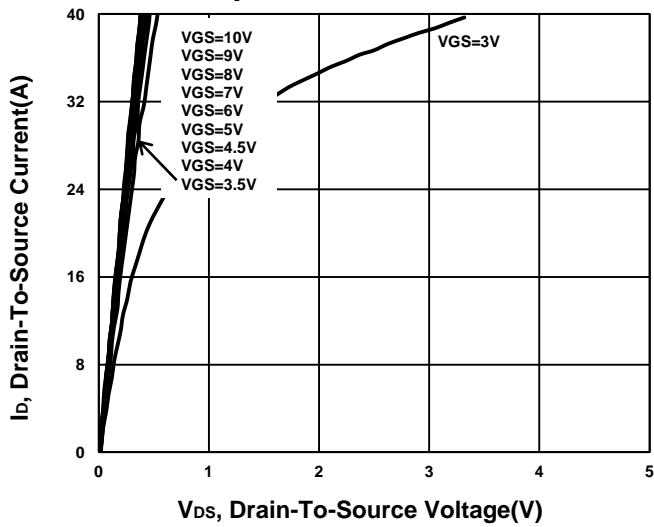
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.8	2.3	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			±100	nA

Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 48V, V_{GS} = 0V$			1	$\mu A$		
		$V_{DS} = 40V, V_{GS} = 0V, T_J = 55^\circ C$			10			
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$		11	16	$m\Omega$		
		$V_{GS} = 10V, I_D = 10A$		9.8	12.5			
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 10A$		50		S		
<b>DYNAMIC</b>								
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1901		$pF$		
Output Capacitance	$C_{oss}$			239				
Reverse Transfer Capacitance	$C_{rss}$			177				
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		0.7		$\Omega$		
Total Gate Charge <sup>2</sup>	$Q_{g(VGS=10V)}$	$V_{DS} = 30V, I_D = 10A$		48		$nC$		
	$Q_{g(VGS=4.5V)}$			27				
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			5				
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			15				
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$		$V_{DS} = 30V, I_D \cong 10A, V_{GS} = 10V, R_{GEN} = 6\Omega$		20			$nS$
Rise Time <sup>2</sup>	$t_r$				12			
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			58				
Fall Time <sup>2</sup>	$t_f$			10				
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>								
Continuous Current	$I_S$				3	A		
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 10A, V_{GS} = 0V$			1.3	V		
Diode Reverse Recovery Time	$t_{rr}$	$I_F = 10A, di/dt = 100A/\mu s$		26		nS		
Diode Reverse Recovery Charge	$Q_{rr}$			17		nC		

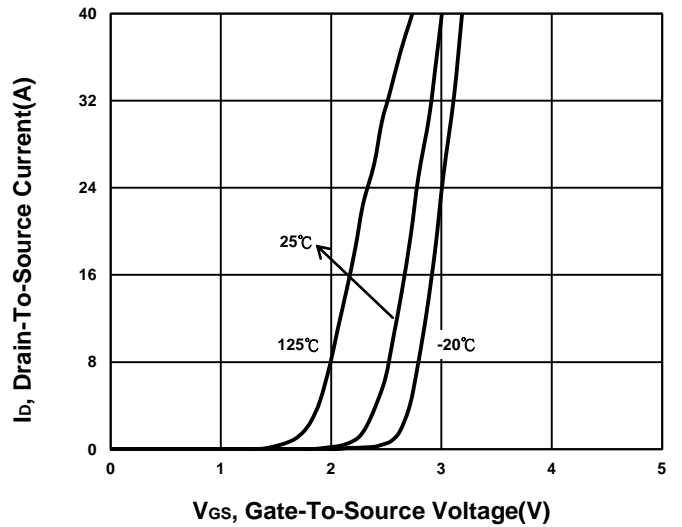
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

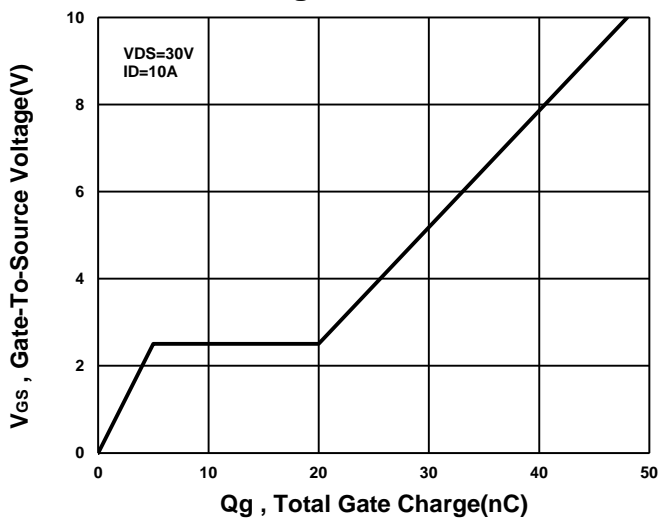
**Output Characteristics**



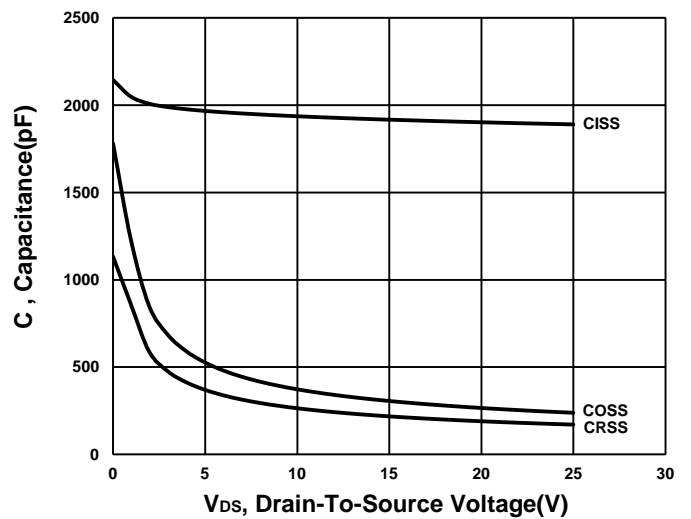
**Transfer Characteristics**



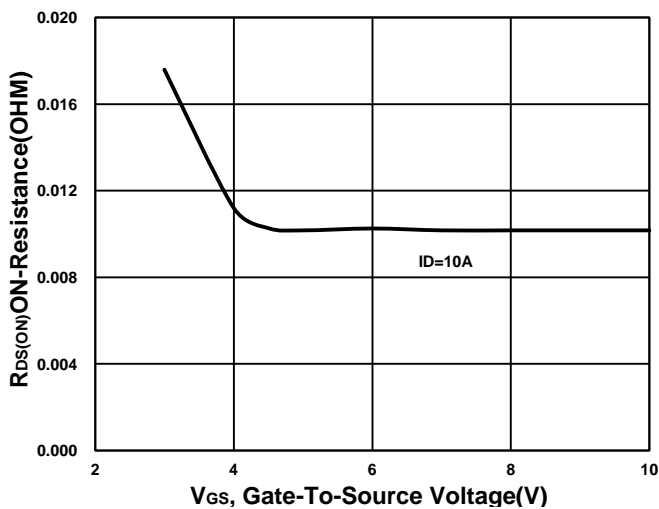
**Gate charge Characteristics**



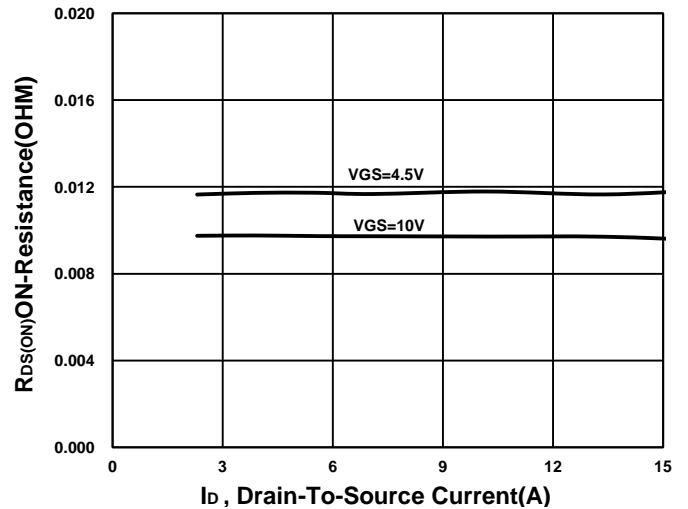
**Capacitance Characteristic**



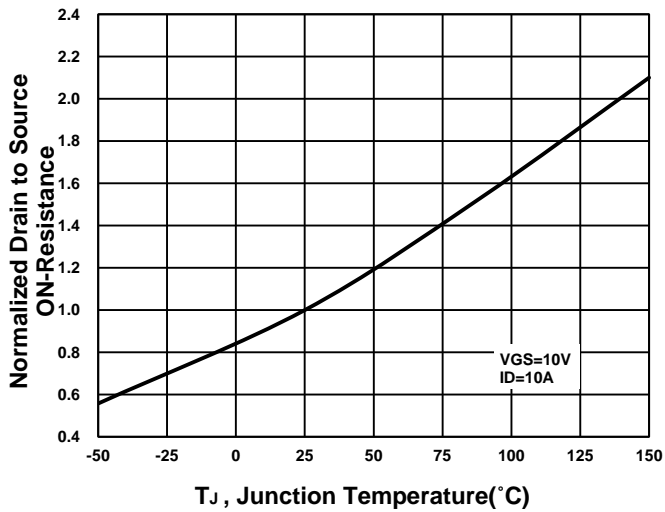
**On-Resistance VS Gate-To-Source**



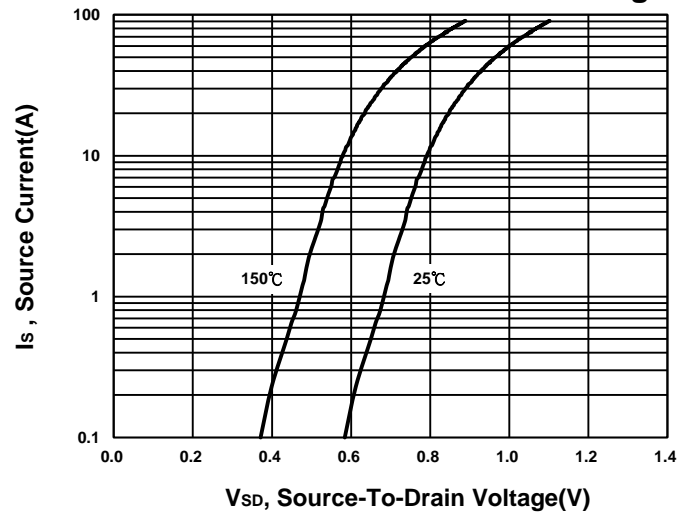
**On-Resistance VS Drain Current**



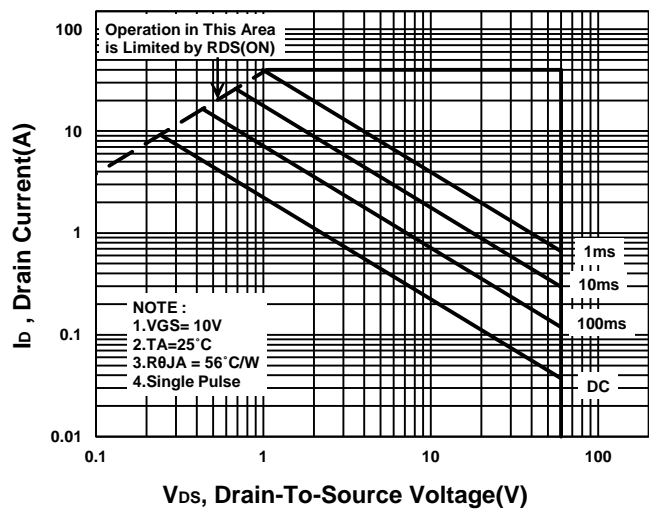
**On-Resistance VS Temperature**



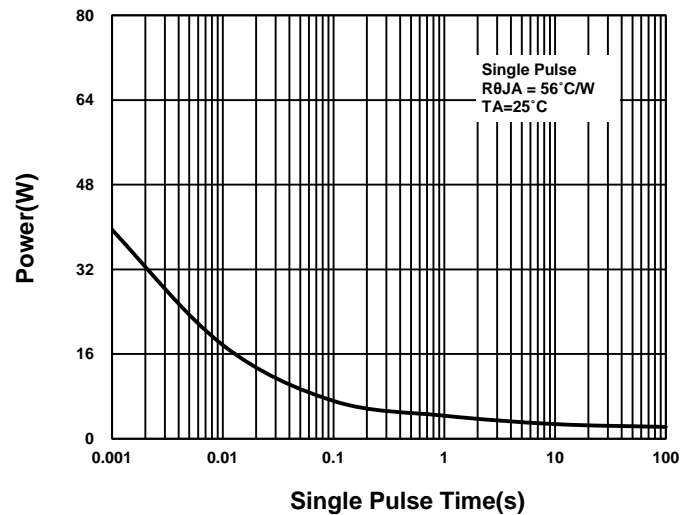
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

